

THGBMNG5D1LBAIL 全新原装 EMMC FLASH

制造商	KIOXIA/TOSHIBA Technology
产品种类	eMMC
RoHS	是
封装	BGA
存储容量	4 Gbit
工作温度	-25° C to +85° C

THGBMNG5D1LBAIL is 4GB density of e-MMC Module product housed in 153 ball BGA package. This unit is utilized advanced TOSHIBA NAND flash device(s) and controller chip assembled as Multi Chip Module. THGBMNG5D1LBAIL has an industry standard MMC protocol for easy use.